DESIGN: cpc_mockup_hdi_1x2_v2
VERSION: 1.01
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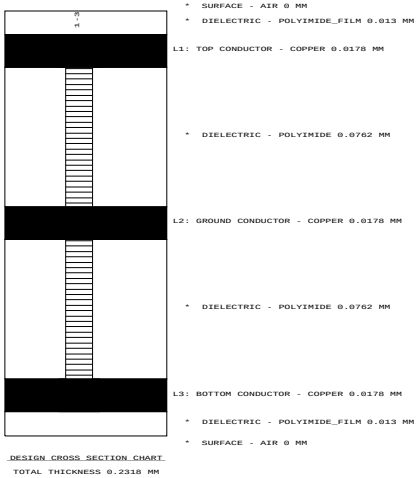
CONTACT: Matthew Jones
Purdue University Dept. of Physics
525 Northwestern Ave
West Lafayette, IN 47901-2036

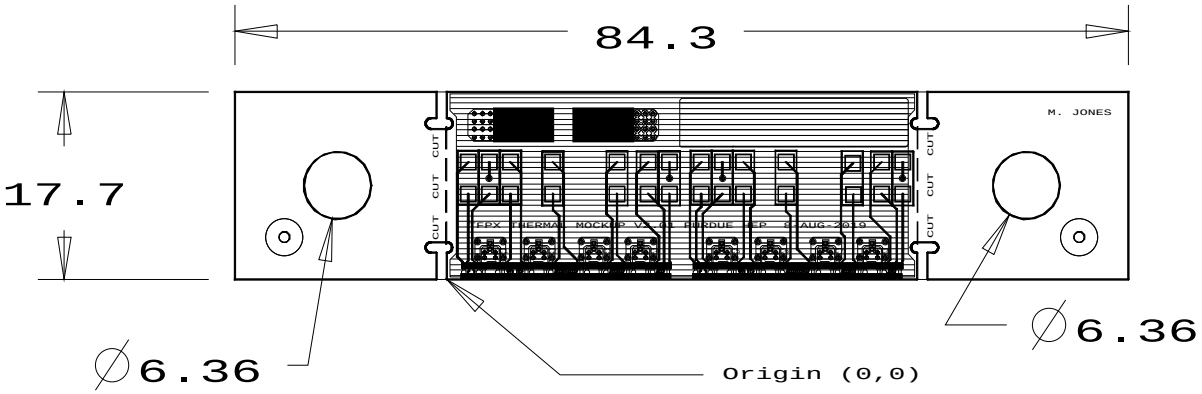
PHONE: 630-309-8187 (cell)
765-496-2464 (office/voicemail)
765-494-5971 (lab)

FAX: 765-494-0706

EMAIL: mjones@physics.purdue.edu



LAYER	CU THICKNESS	DESCRIPTION
TOP	0.01778 MM (0.5 OZ)	TOP SIGNAL ROUTING
GROUND	0.01778 MM (0.5 OZ)	GROUND PLANE
BOTTOM	0.01778 MM (0.5 OZ)	POWER PLANE



CIRCUIT DESCRIPTION:

The manufacturing files provided describe a rectangular flex circuit with a geometry that is approximately 84x18 mm. Circuits may be removed from panel and provided individually.

DESIGN NOTES:

1. All dimensions are in millimeters

2. Minimum line width is 0.100 mm (4 mils)
   Minimum line spacing is 0.09 mm (3.5 mils)
   Smallest drill size is 0.2032 mm (8 mils)
   Total number of holes: 96

3. Origin of the coordinate system for gerber and drill files is (0,0) as indicated on the drawing.

4. This is a 3-layer board. Layer names and copper thickness are as follows:

5. Circuit material is Polyimide film, 1/2 oz copper on all layers. Total thickness is approximately 0.25 mm.
   Layer thickness can be adjusted to optimize manufacturability.

6. Surface finish is ENEPIG - must be wire bondable using wedge bonder with aluminum wire.

7. LPI soldermaks around all solder pads on top layer. Polyimide coverlay film (0.0130 mm thickness) on bottom layer.
   White silkscreen on top layer only.

8. Electrical test required. IPC-356 netlist provided for connectivity testing

DRILL CHART: TOP to BOTTOM			
ALL UNITS ARE IN MILLIMETERS			
FIGURE	SIZE	PLATED	QTY
+	0.2032	PLATED	94
○	3.2	NON-PLATED	2